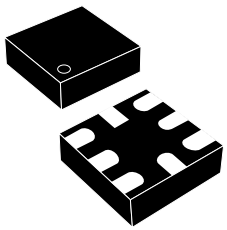
ST2129B

2-bit dual supply level translator without direction control pin, push-pull output

Datasheet - production data



QFN8
(1.4 x 1.2 x 0.55 mm)

Features

- 45 MHz: 90 Mbps (max.) data rate at V_L = 1.8 V, V_{CC} = 3.3 V
- Bi-directional level translation without direction control pin
- Wide voltage range ($V_L \leq V_{CC}$):
  - V_L ranges from 1.65 to 3.6 V
  - V_{CC} ranges from V_L to 5.5 V
- Totem pole driving
- 5.5 V tolerant Enable pin
- ESD performance on all pins: ±2 kV HBM
- Small package and footprint
  QFN8 1.4 x 1.2 x 0.55 mm

Applications

- Low-voltage system level translation
- Mobile phones and other mobile devices

Description

The ST2129B device is a 2-bit dual supply level translator which provides the level shifting capability to allow data transfer in a multi-voltage system. Externally applied voltages, V_{CC} and V_L, set the logic levels on either side of the device. Its architecture allows bi-directional level translation without a control pin.

The ST2129B device accepts V_L from 1.65 to 3.6 V and V_{CC} from V_L to 5.5 V, making it ideal for data transfer between low-voltage ASICs/PLD and higher voltage systems. This device has a tristate output mode which can be used to disable all I/Os.

Table 1. Device summary

Order code	Package	Packing	Package topmark
ST2129BQTR	QFN8 (1.4 x 1.2 x 0.55 mm)	Tape and reel (3000 parts per reel)	1A

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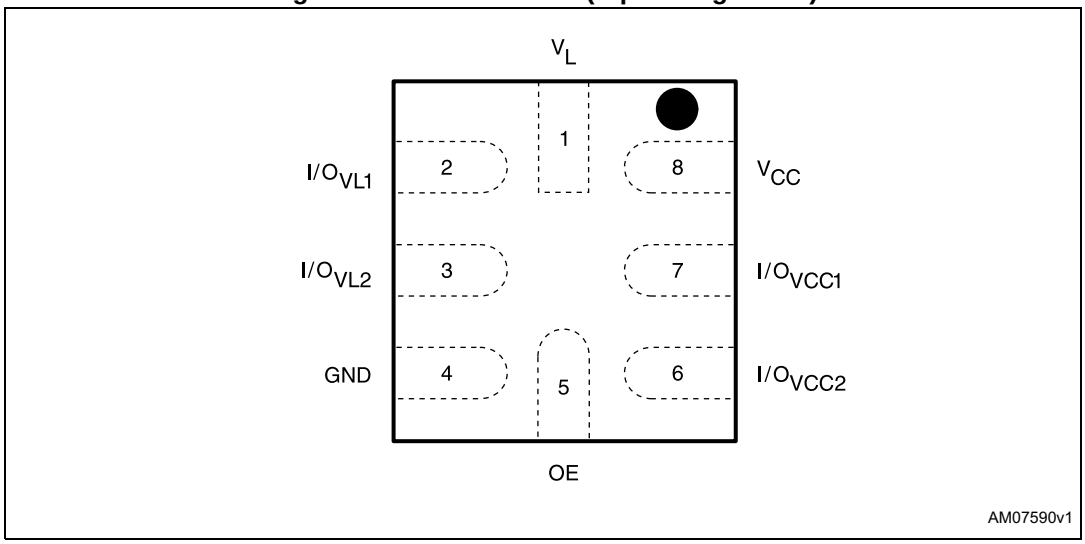
1 Pin settings

1.1 Pin connection

Figure 1. Pin connection (top through view)



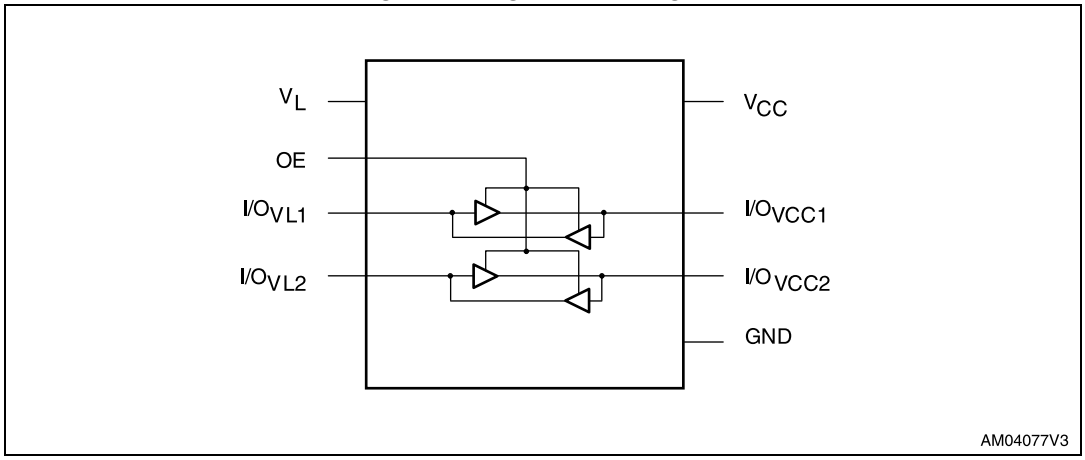
1.2 Pin description

Table 2. Pin description

Pin number	Symbol	Name and function
1	V_L	Supply voltage
2	I/O_{VL1}	Data input/output
3	I/O_{VL2}	Data input/output
4	GND	Ground
5	OE	Output enable
6	I/O_{VCC2}	Data input/output
7	I/O_{VCC1}	Data input/output
8	V_{CC}	Supply voltage

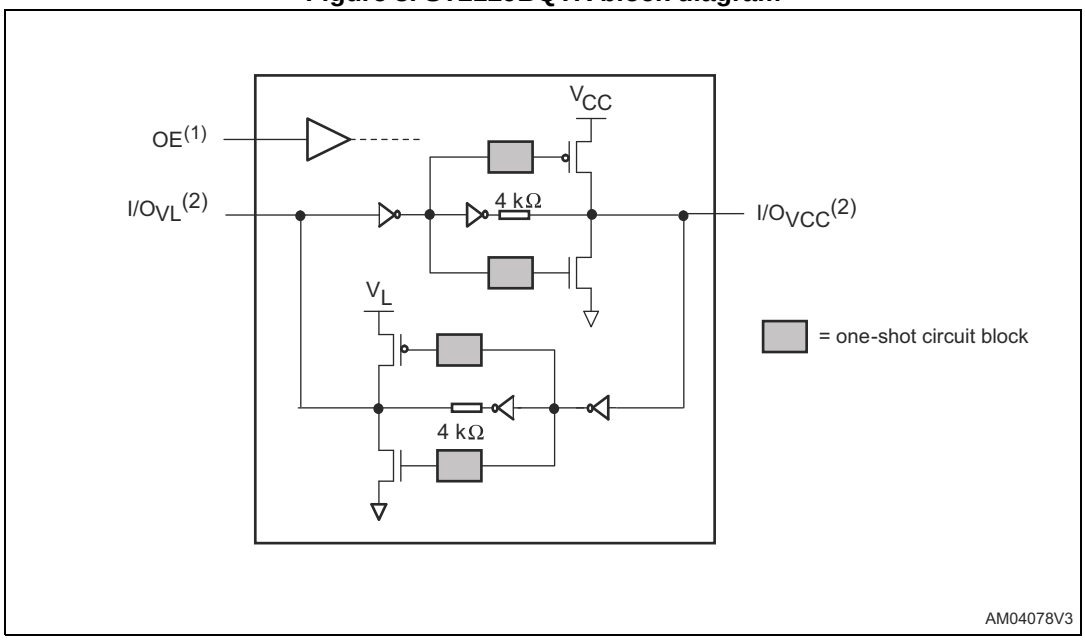
2 Logic diagram

Figure 2. Logic block diagram



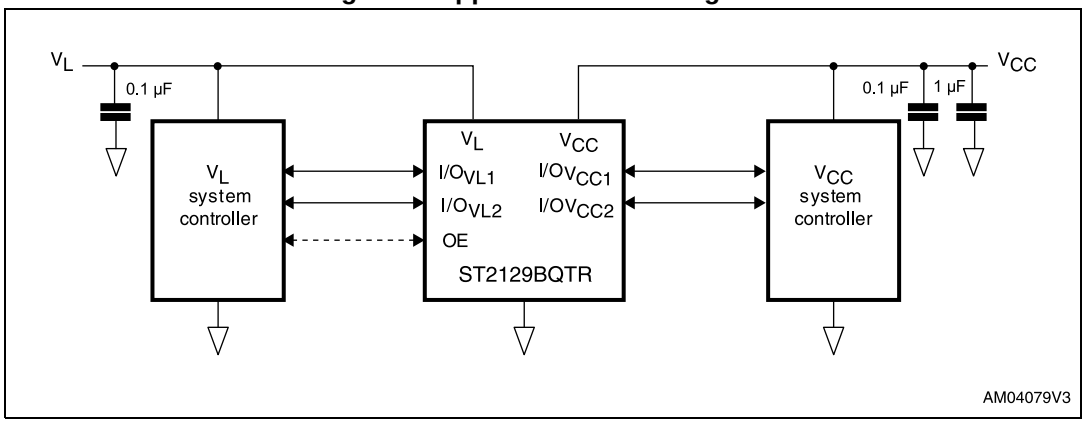
Device block diagrams

Figure 3. ST2129BQTR block diagram



1. When OE is LOW, all I/Os are in high-impedance mode.
2. ST2129BQTR has 2 channels. For simplicity, the above diagram shows only 1 channel.

Figure 4. Application block diagram



3 Supplementary notes

3.1 Driver requirement

For proper operation, the driver from each side of the device must have the capability to source and sink a minimum of 1 mA current. The device architecture requires the driver to source/sink maximum current of (V_{CC}/4) mA to/from the weak 4 kΩ output buffer.

3.2 Load driving capability

To support the architecture that allows level translation without direction pin, the one-shot transistor is turned ON only during state transition at the output side. After the one-shot transistor is turned OFF, only the 4 kΩ resistor maintains the output logic state. So, a resistive load or pull-up resistor less than 50 kΩ is not recommended for proper operation.

3.3 Truth table

Table 3. Truth table

Enable	Bi-directional input/output	
OE	**I/O$_{VCC}$**	**I/O$_{VL}$**
H(1)	H(2)	H(1)
H(1)	L	L
L	Z(3)	Z(3)

1. High level V_L power supply referred.
2. High level V_{CC} power supply referred.
3. Z = high impedance.

4 Maximum ratings

Stressing the device above the rating listed in *Table 4: Absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in *Table 5: Recommended operating conditions* of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_L	Supply voltage	-0.3 to 4.6	V
V_{CC}	Supply voltage	-0.3 to 6.5	V
V_{OE}	DC control input voltage	-0.3 to 6.5	V
$V_{I/OVL}$	DC I/O_{VL} input voltage (OE = GND or V_L)	-0.3 to V_L + 0.3	V
$V_{I/OVCC}$	DC I/O_{VCC} input voltage (OE = GND or V_L)	-0.3 to V_{CC} + 0.3	V
I_{IK}	DC input diode current	-20	mA
$I_{I/OVL}$	DC output current	±25	mA
$I_{I/OVCC}$	DC output current	±25	mA
I_{SCTOUT}	Short-circuit duration, continuous	40	mA
P_D	Power dissipation	500	mW
T_{STG}	Storage temperature	-65 to 150	°C
T_L	Lead temperature (10 seconds)	300	°C
ESD	Electrostatic discharge protection (HBM)	±2	kV

Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_L	Supply voltage	1.65	–	3.6	V
V_{CC}	Supply voltage	V_L	–	5.5	V
V_{OE}	Input voltage (OE output enable pin, V_L power supply referred)	0	–	3.6	V
$V_{I/OVL}$	I/O_{VL} voltage	0	–	V_L	V
$V_{I/OVCC}$	I/O_{VCC} voltage	0	–	V_{CC}	V
T_{OP}	Operating temperature	-40	–	85	°C
dt/dV	Input rise and fall time	0	–	1	ns/V

5 Electrical characteristics

5.1 DC characteristics

Over recommended operating conditions unless otherwise noted. All typical values are at T_A = 25 °C.

Table 6. DC characteristics

Symbol	Parameter	V_L	V_{CC}	Test conditions	Value					Unit
					T_A = 25 °C			-40 to 85 °C		
					Min.	Typ.	Max.	Min.	Max.	
V_{IHL}	High-level input voltage (I/O_{VL})	1.65 to 3.6	V_L to 5.5		0.8 V_L	–	–	0.8 V_L	–	V
V_{ILL}	Low-level input voltage (I/O_{VL})	1.65 to 3.6	V_L to 5.5		–	–	0.2 V_L	–	0.2 V_L	V
V_{IHC}	High-level input voltage (I/O_{VCC})	1.65 to 3.6	V_L to 5.5		0.8 V_{CC}	–	–	0.8 V_{CC}	–	V
V_{ILC}	Low-level input voltage (I/O_{VCC})	1.65 to 3.6	V_L to 5.5		–	–	0.2 V_{CC}	–	0.2 V_{CC}	V
V_{IH-OE}	High-level input voltage (OE)	1.65 to 3.6	V_L to 5.5		0.8 V_L	–	–	0.8 V_L	–	V
V_{IL-OE}	Low-level input voltage (OE)	1.65 to 3.6	V_L to 5.5		–	–	0.2 V_L	–	0.2 V_L	V
V_{OHL}	High-level output voltage (I/O_{VL})	1.65 to 3.6	V_L to 5.5	IO = -60 µA	V_L - 0.4	–	–	V_L - 0.4	–	V
V_{OLL}	Low-level output voltage (I/O_{VL})	1.65 to 3.6	V_L to 5.5	IO = +60 µA	–	–	0.4	–	0.4	V
V_{OHC}	High-level output voltage (I/O_{VCC})	1.65 to 3.6	V_L to 5.5	IO = -60 µA	V_{CC} - 0.4	–	–	V_{CC} - 0.4	–	V

Table 6. DC characteristics (continued)

Symbol	Parameter	V_L	V_{CC}	Test conditions	Value					Unit
					T_A = 25 °C			-40 to 85 °C		
					Min.	Typ.	Max.	Min.	Max.	
V_{OLC}	Low-level output voltage (I/O_{VCC})	1.65 to 3.6	V_L to 5.5	IO = +60 µA	–	–	0.4	–	0.4	V
I_{OE}	Control input leakage current (OE)	1.65 to 3.6	V_L to 5.5	V_I = GND or V_L	–	–	0.1	–	1	µA
I_{IO_LKG}	High-impedance leakage current (I/O_{VL}, I/O_{VCC})	1.65 to 3.6	V_L to 5.5	OE = GND I/O_{VL} = high I/O_{VCC} = low	–	–	0.1	–	1	µA
				OE = GND I/O_{VL} = low I/O_{VCC} = high	–	–	0.1	–	1	µA
I_{QVCC}	Quiescent supply current V_{CC}	1.65 to 3.6	V_L to 5.5	OE = V_L	—	–	3.5	–	4.5	µA
I_{QVL}	Quiescent supply current V_L	1.65 to 3.6	V_L to 5.5	OE = V_L	–	–	0.1	–	1	µA
$I_{Z\text{-}VCC}$	High-impedance quiescent supply current V_{CC}	1.65 to 3.6	V_L to 5.5	OE = GND I/O = Hi-Z	–	–	0.1	–	1	µA
$I_{Z\text{-}VL}$	High-impedance quiescent supply current V_L	1.65 to 3.6	V_L to 5.5	OE = GND I/O = Hi-Z	–	–	0.1	–	1	µA

5.2 AC characteristics

Load C_L = 15 pF; driver $t_r = t_f \leq$ 6 ns over temperature range -40 °C to 85 °C.

Table 7. AC characteristics - test conditions: V_L = 1.65 - 1.95 V

Symbol	Parameter		V_{CC} = V_L - 1.95 V		V_{CC} = 2.3 - 2.7 V		V_{CC} = 3.0 - 3.6 V		V_{CC} = 4.5 - 5.5 V		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{RVcc}	Rise time I/O_{Vcc}		-	5.2	-	3.2	-	2.4	-	1.8	ns
t_{FVcc}	Fall time I/O_{Vcc}		-	3.2	-	1.5	-	1.3	-	1.2	ns
t_{RVL}	Rise time I/O_{VL}		-	3.3	-	3.3	-	3.3	-	3.3	ns
t_{FVL}	Fall time I/O_{VL}		-	1.5	-	1.4	-	1.4	-	1.3	ns
$t_{I/OVL-Vcc}$	Propagation delay time										
	I/O_{VL-LH} to I/O_{Vcc-LH}	t_{PLH}	-	7.6	-	5.8	-	5.0	-	4.4	ns
	I/O_{VL-HL} to I/O_{Vcc-HL}	t_{PHL}	-	4.6	-	3.9	-	3.9	-	3.5	ns
$t_{I/OVcc-VL}$	Propagation delay time										
	I/O_{Vcc-LH} to I/O_{VL-LH}	t_{PLH}	-	7.1	-	6.6	-	4.8	-	4.6	ns
	I/O_{Vcc-HL} to I/O_{VL-HL}	t_{PHL}	-	5.3	-	5.1	-	4.3	-	4.1	ns
t_{PZL}	Output enable time t_{PZL}		-	28	-	28	-	28	-	28	ns
t_{PZH}	Output enable time t_{PZH}		-	90	-	90	-	90	-	90	ns
t_{PLZ}	Output disable time t_{PLZ}			120	-	120	-	120	-	120	ns
t_{PHZ}	Output disable time t_{PHZ}			80	-	60	-	50	-	50	ns
D_R	Data rate(1)		56	-	90	-	90	-	90	-	Mbps

1. Data rate is guaranteed based on the condition that output I/O signal rise/fall time is less than 15% of period of input I/O signal; input I/O signal is at 50% duty cycle and output I/O signal duty cycle deviation is less than 50% ± 10%.

Table 8. AC characteristics - test conditions: V_L = 2.3 - 2.7 V

Symbol	Parameter		V_{CC} = V_L - 2.7 V		V_{CC} = 3.0 - 3.6 V		V_{CC} = 4.5 - 5.5 V		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{RVcc}	Rise time I/O_{Vcc}		-	3.3	-	2.2	-	1.7	ns
t_{FVcc}	Fall time I/O_{Vcc}		-	1.7	-	1.6	-	1.4	ns
t_{RVL}	Rise time I/O_{VL}		-	2.2	-	2.2	-	1.9	ns
t_{FVL}	Fall time I/O_{VL}		-	1.3	-	1.2	-	1.2	ns
$t_{I/OVL-Vcc}$	Propagation delay time								
	I/O_{VL-LH} to I/O_{Vcc-LH}	t_{PLH}	-	4.8	-	4.3	-	3.9	ns
	I/O_{VL-HL} to I/O_{Vcc-HL}	t_{PHL}	-	3.7	-	3.3	-	2.9	ns
$t_{I/OVcc-VL}$	Propagation delay time								
	I/O_{Vcc-LH} to I/O_{VL-LH}	t_{PLH}	-	3.9	-	3.5	-	3.5	ns
	I/O_{Vcc-HL} to I/O_{VL-HL}	t_{PHL}	-	3.6	-	3.5	-	3.4	ns
t_{PZL}	Output enable time t_{PZL}		-	25	-	25	-	25	ns
t_{PZH}	Output enable time t_{PZH}		-	100	-	100	-	70	ns
t_{PLZ}	Output disable time t_{PLZ}		-	90	-	90	-	90	ns
t_{PHZ}	Output disable time t_{PHZ}		-	50	-	50	-	50	ns
D_R	Data rate(1)		90	-	136	-	158	-	Mbps

1. Data rate is guaranteed based on the condition that output I/O signal rise/fall time is less than 15% of period of input I/O signal; input I/O signal is at 50% duty cycle and output I/O signal duty cycle deviation is less than 50% ± 10%.

Table 9. AC characteristics - test conditions: V_L = 3.0 - 3.6 V

Symbol	Parameter		V_{CC} = V_L - 3.6 V		V_{CC} = 4.5 - 5.5 V		Unit
			Min.	Max.	Min.	Max.	
t_{RVcc}	Rise time I/O_{Vcc}		-	2.1	-	1.7	ns
t_{FVcc}	Fall time I/O_{Vcc}		-	1.3	-	1.3	ns
t_{RVL}	Rise time I/O_{VL}		-	1.6	-	1.5	ns
t_{FVL}	Fall time I/O_{VL}		-	1.1	-	1.1	ns
$t_{I/OVL-Vcc}$	Propagation delay time						
	I/O_{VL-LH} to I/O_{Vcc-LH}	t_{PLH}	-	4.1	-	4.1	ns
	I/O_{VL-HL} to I/O_{Vcc-HL}	t_{PHL}	-	2.9	-	2.6	ns
$t_{I/OVcc-VL}$	Propagation delay time						
	I/O_{Vcc-LH} to I/O_{VL-LH}	t_{PLH}	-	4.0	-	4.0	ns
	I/O_{Vcc-HL} to I/O_{VL-HL}	t_{PHL}	-	2.6	-	2.5	ns
t_{PZL}	Output enable time t_{PZL}		-	15	-	15	ns
t_{PZH}	Output enable time t_{PZH}		-	70	-	15	ns
t_{PLZ}	Output disable time t_{PLZ}		-	70	-	70	ns
t_{PHZ}	Output disable time t_{PHZ}		-	50	-	50	ns
D_R	Data rate(1)		144	-	186	-	Mbps

1. Data rate is guaranteed based on the condition that output I/O signal rise/fall time is less than 15% of period of input I/O signal; input I/O signal is at 50% duty cycle and output I/O signal duty cycle deviation is less than 50% ± 10%.

6 Test circuit

Figure 5. Test circuit

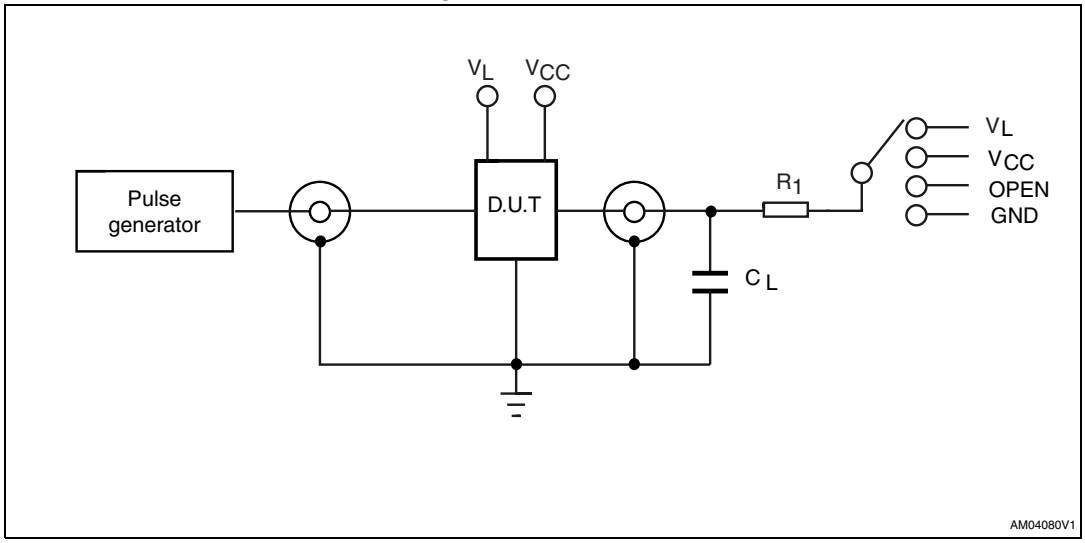


Table 10. Test circuit switches

Test	C_L	R_1	Switch
t_{PLH}, t_{PHL}	15 pF	20 kΩ	Open
t_r, t_f	15 pF	20 kΩ	Open
t_{PZL}, t_{PLZ}	15 pF	20 kΩ	V_L or V_{CC}
t_{PZH}, t_{PHZ}	15 pF	20 kΩ	GND

Table 11. Waveform symbol value

Symbol	Driving I/O_{VL}		Driving I/O_{VCC}	
	1.65 V ≤ V_L ≤ V_{CC} ≤ 2.5 V	**3.3 V ≤ V_L ≤ V_{CC} ≤ 5.5 V**	**1.65 V ≤ V_L ≤ V_{CC} ≤ 2.5 V**	**3.3 V ≤ V_L≤ V_{CC} ≤ 5.5 V**
V_{IH}	V_L	V_L	V_{CC}	V_{CC}
V_{IM}	50% V_L	50% V_L	50% V_{CC}	50% V_{CC}
V_{OM}	50% V_{CC}	50% V_{CC}	50% V_L	50% V_L

Figure 6. Waveform - propagation delay (f = 1 MHz, 50% duty cycle)

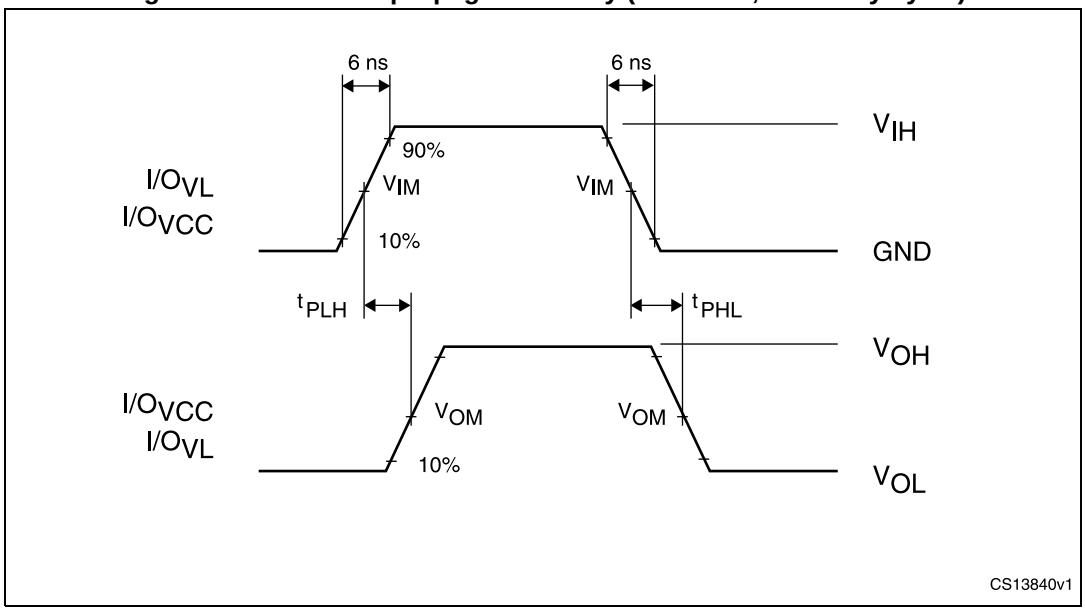
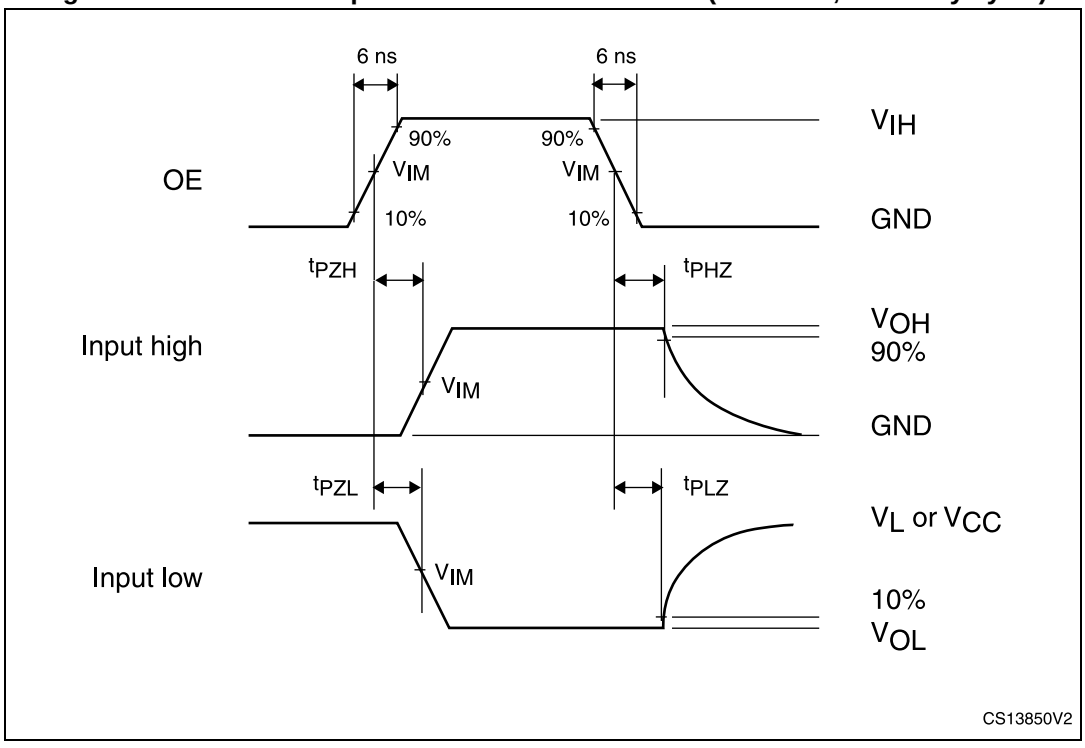


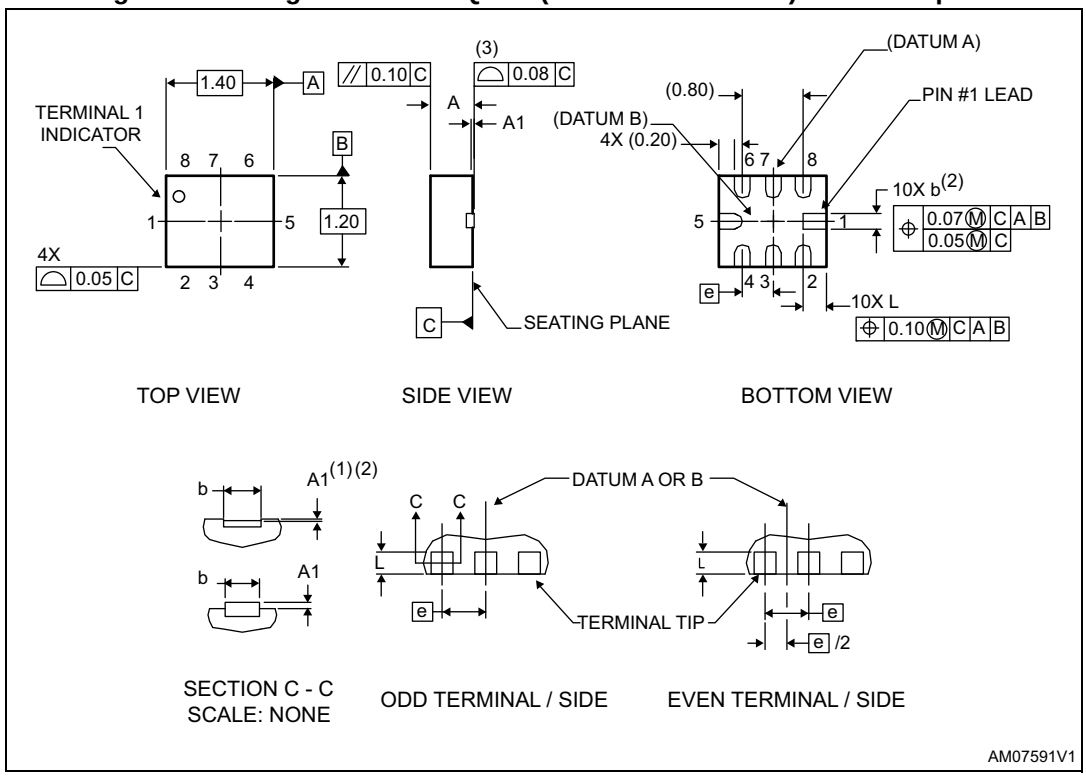
Figure 7. Waveform - output enable and disable time (f = 1 MHz, 50% duty cycle)



7 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK is an ST trademark.

Figure 8. Package outline for QFN8 (1.4 x 1.2 x 0.55 mm) - 0.40 mm pitch



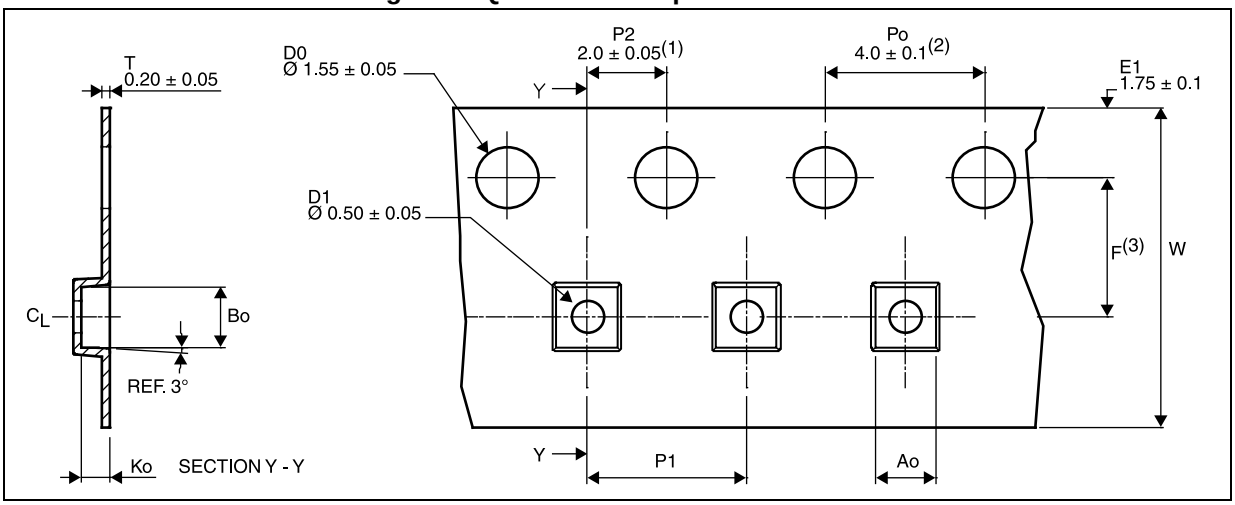
1. Dimension b applies to metallized terminal and is measured between 0.10 and 0.20 mm from the terminal tip. If the terminal has the optional radius on the other end of the terminal. Dimension b should not be measured in that radius area.
2. Applied only for terminals.
3. Bilateral coplanarity zone applies to the exposed heatsink slug as well as the terminals.
4. Dimensions and tolerancing conform to ASME Y14.5M - 1994.

Table 12. Mechanical data for QFN8 (1.4 x 1.2 x 0.55 mm) - 0.40 mm pitch

Symbol	Dimensions (mm)			Note
	Min.	Nom.	Max.	
A	0.50	0.55	0.60	
A1	0.00	-	0.05	
b	0.15	0.20	0.25	(1)
B	0	-	12°	(2)
e	0.40 BSC			
N	8			(3)
L	0.25	0.30	0.35	

1. Dimension b applies to the metallized terminal and is measured between 0.10 and 0.20 mm from the terminal tip. If the terminal has the optional radius on the other end of the terminal. Dimension b should not be measured in that radius area.
2. All dimensions are in millimeters, B is in degrees.
3. N is the total number of terminals.

Figure 9. QFN8 carrier tape - 8 mm width

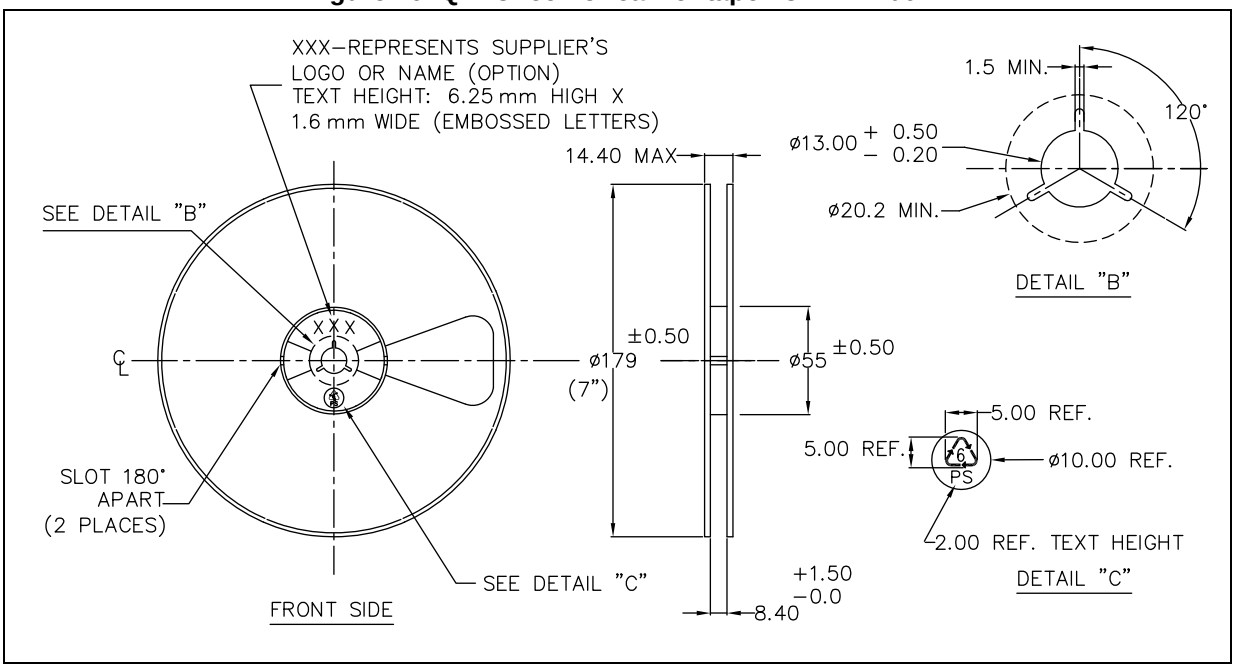


1. Measured from centerline of sprocket hole to centerline of pocket.
2. Cumulative tolerance of 10 sprocket holes is ± 0.20.
3. Measured from centerline of sprocket hole to centerline of pocket.
4. Other material available.
5. Typical SR of form tape max. 10° Ω/SR.
6. All dimensions are in millimeters unless otherwise stated.

Table 13. QFN8 carrier tape dimensions - 8 mm width

	Carrier tape					
Symbol	Ao	Bo	Ko	F	P1	W
Dimensions	1.52 ± 0.05	1.52 ± 0.05	0.73 ± 0.05	3.50 ± 0.05	4.00 ± 0.10	8.00 ± 0.10

Figure 10. QFN8 reel for carrier tape - 8 mm width



8 Revision history

Table 14. Document revision history

Date	Revision	Changes
14-Jun-2012	1	Initial release.
18-Feb-2013	2	Updated document status (production data). Updated *Description* (corrected RPNs), *Description* moved to page 1. Added carrier tape (*Figure 9* and *Table 13*). Minor corrections throughout document.

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